

Interscale Flexible Heat Conductor (FHC), 20 mm

Power Utilities



Conductor block expands/contracts vertically to compensate for tolerance stack up and optimizes surface contact and pressure along the thermal path; eliminates the need for a thermal gap pad.

认证



功能

Designed for Intel, AMD, Via, Freescale, NVidia and Texas Instrument processors that employ a BGA socket

Provides industry-leading conduction cooling performance, 10% improvement over current conduction cooling methods

Patent pending conduction cooling solution for small form factor electronics

Secured to PCB with thermally conductive adhesive tape

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Compatible with Interscale C enclosures

技术参数

Table 1/1					
物料号	类型	搭配	包装数量	深度	宽度
24830-005	热导体	仪器箱	1	22 mm	22 mm

警告

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